

The **paddle cell** plating lab tool operates in a rack configuration with substrates aligned vertically. The main feature of the system is the paddle unit, which moves in a short distance parallel to the substrate surface to create specific and very uniform flow conditions. The benchtop system fits into standard exhausts.

## Basic scope

- Paddle cell, tank volume 15-25l, anode, wafer holder

## Accessories

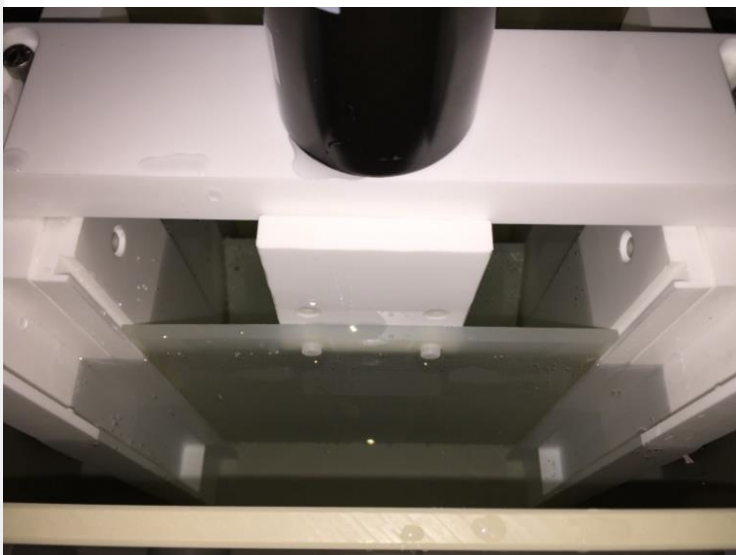
- Temperature control
- pH-control

## Applications

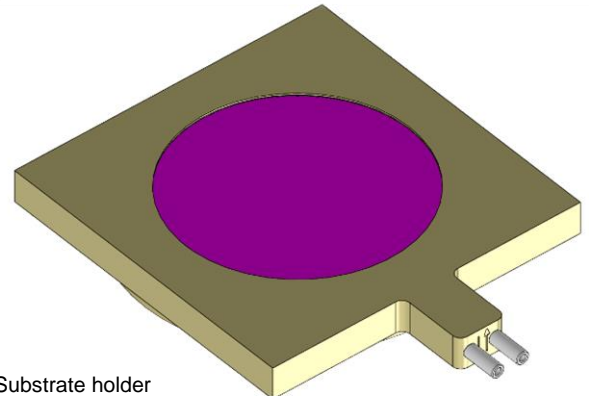
- Electroplating of NiFe, Cu, Au, Sn or Ag on semiconductor substrates

## Advantages

- Very uniform flow conditions
- Modular design



Paddle unit moving vertically for homogeneous flow conditions



Substrate holder

